

Description

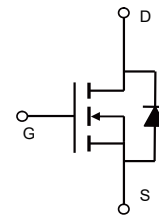
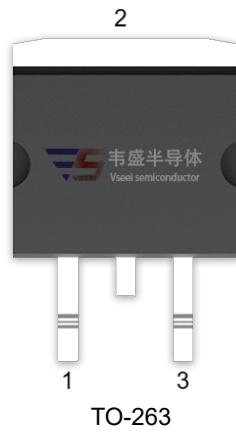
The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- $V_{DS}=85V, I_D=95A$
 $R_{DS(ON)}=5.4m\Omega$, typical (TO-220)@ $V_{GS}=10V$
 $R_{DS(ON)}=5.2m\Omega$, typical (TO-263)@ $V_{GS}=10V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating



Schematic

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST08N050	VST08N050-T3	TO-263	-	-	-

Absolute Maximum Ratings ($T_C=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	85	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	95	A
Drain Current-Continuous($T_C=100^{\circ}C$)	$I_D(100^{\circ}C)$	70	A
Pulsed Drain Current	I_{DM}	380	A
Maximum Power Dissipation	P_D	125	W
Derating factor		0.83	W/ $^{\circ}C$
Single pulse avalanche energy (Note 5)	E_{AS}	599	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^{\circ}C$

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	$R_{\theta JC}$	1.2	$^{\circ}\text{C/W}$
Thermal Resistance,Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	60	$^{\circ}\text{C/W}$

Electrical Characteristics ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	85		-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =85V, V _{GS} =0V	-	-	1	μA	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	3.0	4.0	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =45A	TO-220	-	5.4	5.8	mΩ
			TO-263		5.2	5.8	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =45A		60	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C _{iss}	V _{DS} =40V, V _{GS} =0V, F=1.0MHz	-	3550	-	PF	
Output Capacitance	C _{oss}		-	540	-	PF	
Reverse Transfer Capacitance	C _{rss}		-	22	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t _{d(on)}	V _{DD} =40V, I _D =45A V _{GS} =10V, R _G =1.6Ω	-	14.5	-	nS	
Turn-on Rise Time	t _r		-	12	-	nS	
Turn-Off Delay Time	t _{d(off)}		-	35	-	nS	
Turn-Off Fall Time	t _f		-	13	-	nS	
Total Gate Charge	Q _g	V _{DS} =40V, I _D =45A, V _{GS} =10V	-	67	-	nC	
Gate-Source Charge	Q _{gs}		-	20		nC	
Gate-Drain Charge	Q _{gd}		-	20		nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _S =45A	-		1.2	V	
Diode Forward Current (Note 2)	I _S		-	-	95	A	
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = I _S di/dt = 100A/μs (Note3)	-	66	-	nS	
Reverse Recovery Charge	Q _{rr}		-	140	-	nC	

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design, and the maximum temperature of 175°C may be used if the PCB allows it.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition : $T_J=25^{\circ}\text{C}, V_{DD}=40V, V_G=10V, L=0.5mH, R_G=25\Omega$

Typical Electrical and Thermal Characteristics

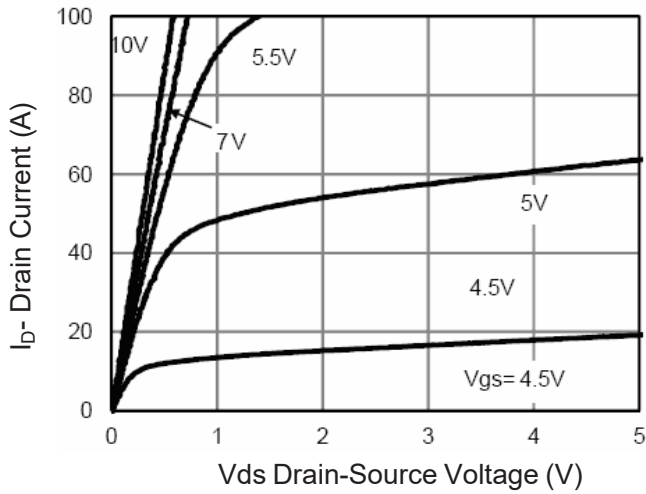


Figure 1 Output Characteristics

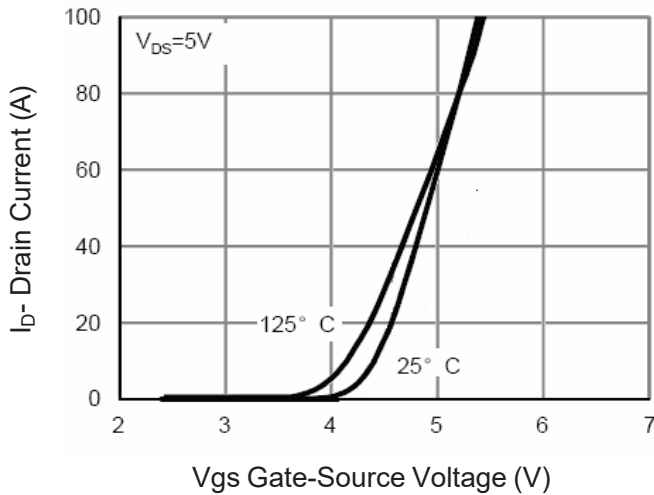


Figure 2 Transfer Characteristics

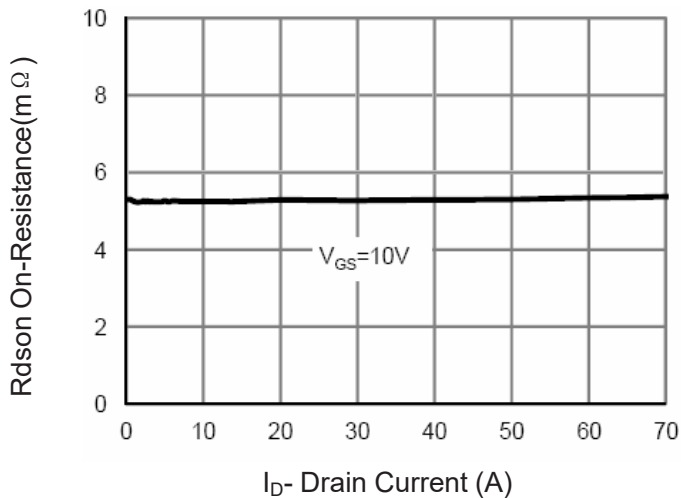


Figure 3 Rdson- Drain Current

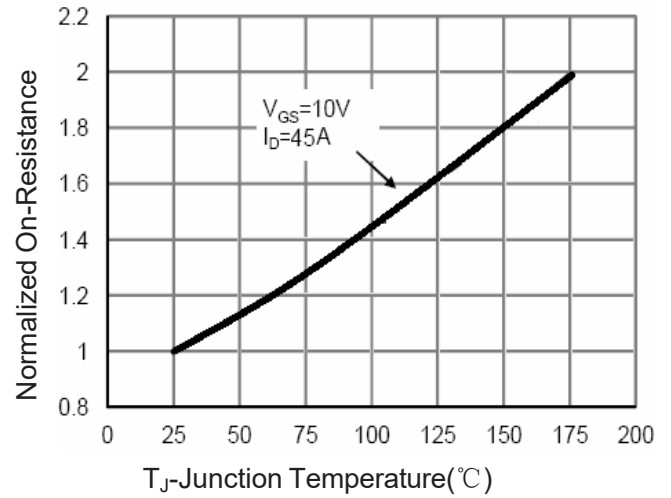


Figure 4 Rdson-Junction Temperature

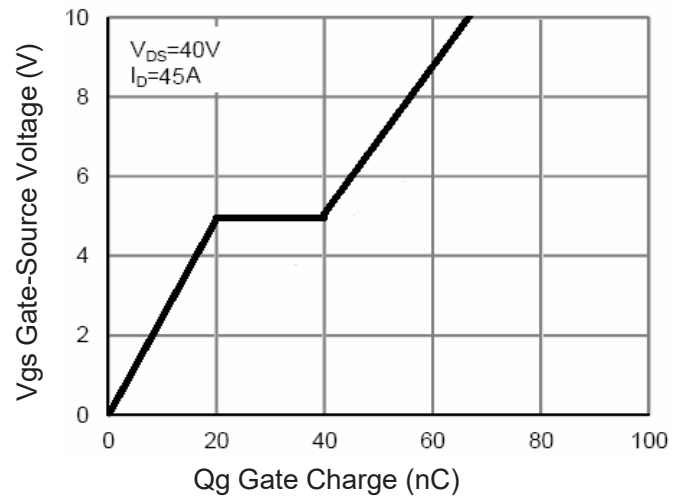


Figure 5 Gate Charge

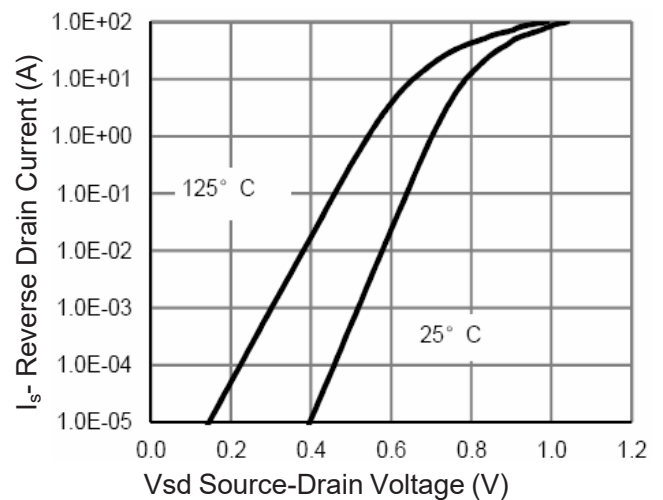
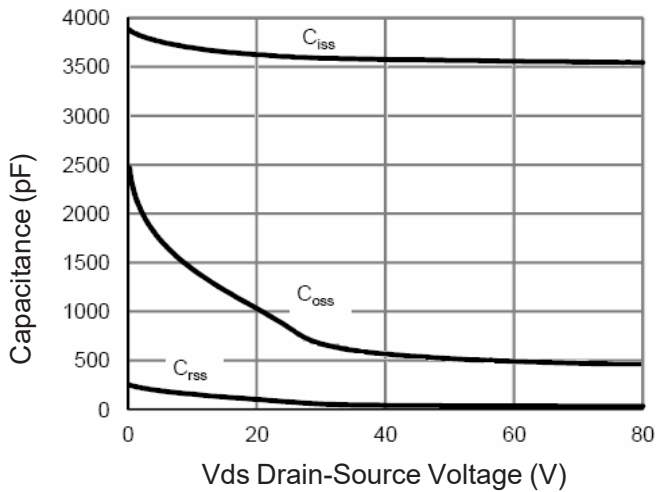
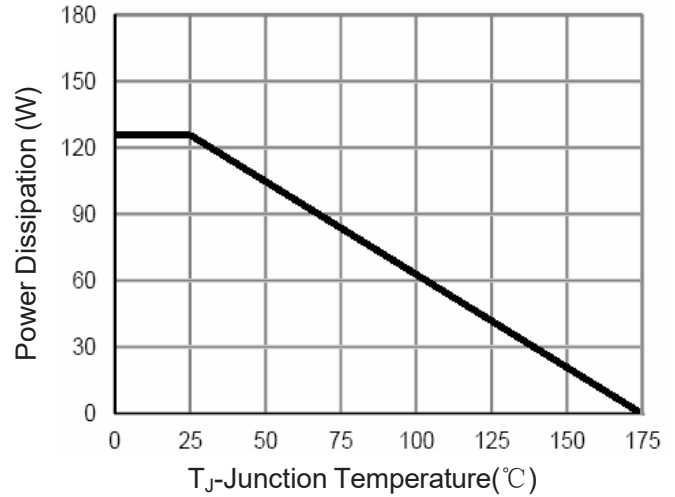
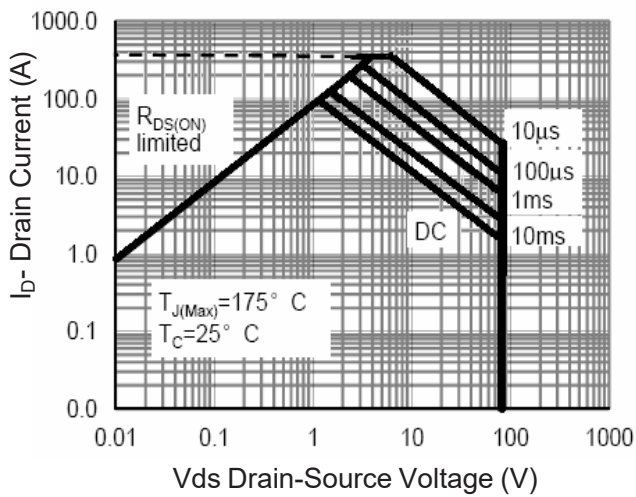
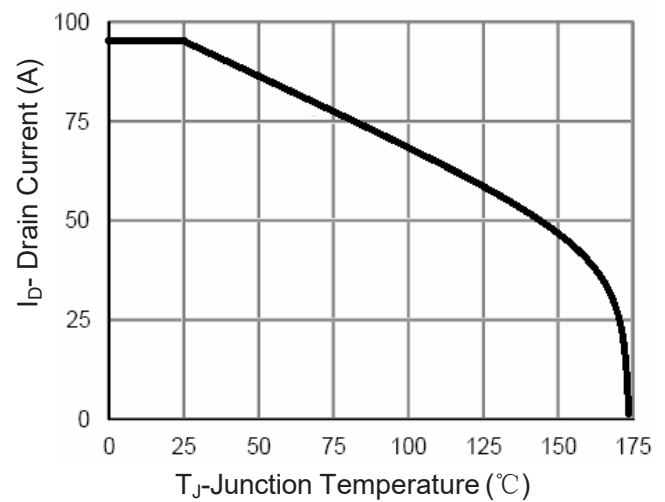
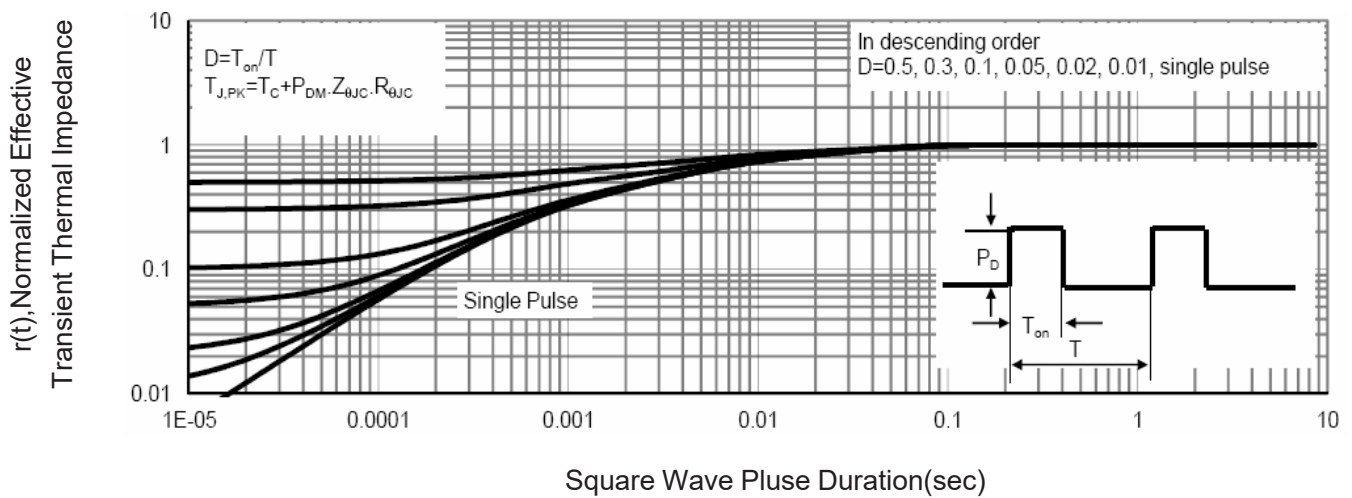


Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area

Figure 10 Current De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance